

1988-179983 [26] WPIDS
DNN N1988-137431 DNC C1988-080419
TI Bonding wire having high fracture strength - obtd. by hot working alloy
ingot of boron and copper, soln. treating, quenching, cold
working and ageing.

DC L03 M26

PA (SUMM) SUMITOMO METAL MINING CO

CYC 1

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ADT JP 63118033 A JP 1986-263661 19861107

PRAI JP 1986-263661 19861107

AB JP 63118033 A UPAB: 19930923

Bonding wire comprises by wt. 0.0001-0.02% B, and balance high
purity Cu of 99.999% purity, having 25-32
kg/mm² fracture strength, and 35-41 Vickers hardness of ball hardness.

The bonding wire is made by hot working the alloy ingot, soln.
treating, followed by quenching; cold working and aging.

USE - The bonding wire made by the method, makes the loop wire
conditions pref., as it has high fracture strength, and does not damage
semiconductor devices on bonding the wire, as it has low hardness (in Hv)
and high ball-neck strength after ball forming.

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